



N-Channel 200-V (D-S) 175°C MOSFET

PRODUCT SUMMARY

V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A)
200	0.090 @ $V_{GS} = 10$ V	19
	0.105 @ $V_{GS} = 6$ V	17.5

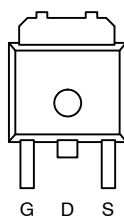
FEATURES

- TrenchFET® Power MOSFET
- 175°C Junction Temperature
- PWM Optimized
- 100% R_g Tested

APPLICATIONS

- Primary Side Switch

TO-252



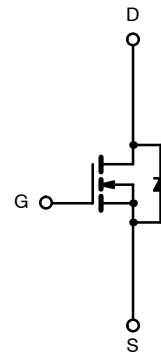
Top View

Ordering Information:

SUD19N20-90

SUD19N20-90—E3 (Lead Free)

Drain Connected to Tab



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	200	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current ($T_J = 175^\circ\text{C}$) ^b	$T_C = 25^\circ\text{C}$	I_D	19	A
	$T_C = 125^\circ\text{C}$		11	
Pulsed Drain Current		I_{DM}	40	
Continuous Source Current (Diode Conduction)		I_S	19	
Avalanche Current		I_{AR}	19	
Repetitive Avalanche Energy (Duty Cycle $\leq 1\%$)	$L = 0.1$ mH	E_{AR}	18	mJ
Maximum Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	136 ^b	W
	$T_A = 25^\circ\text{C}$		3 ^a	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to 175	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient ^a	$t \leq 10$ sec	R_{thJA}	15	18	$^\circ\text{C/W}$
	Steady State		40	50	
Junction-to-Case (Drain)		R_{thJC}	0.85	1.1	

Notes

a. Surface Mounted on 1" x 1" FR4 Board.

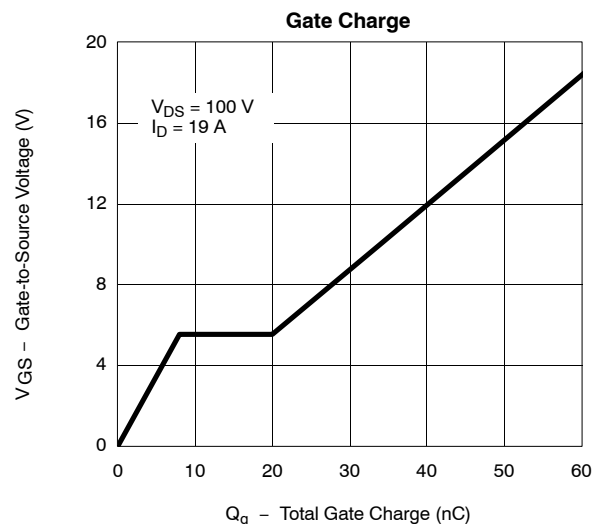
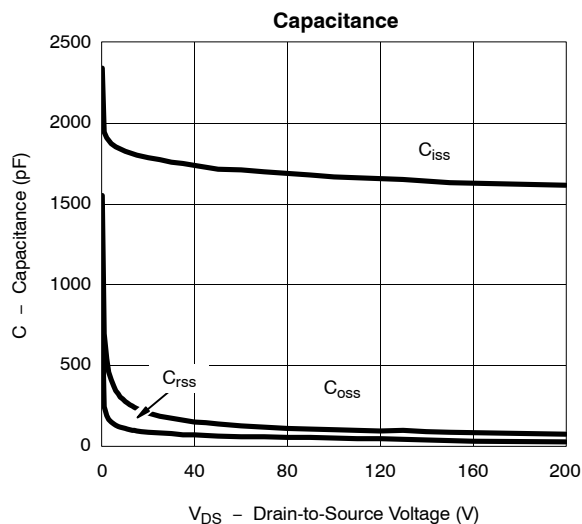
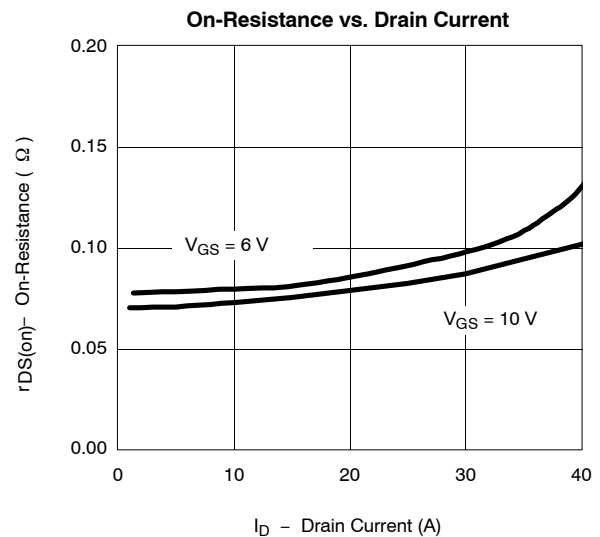
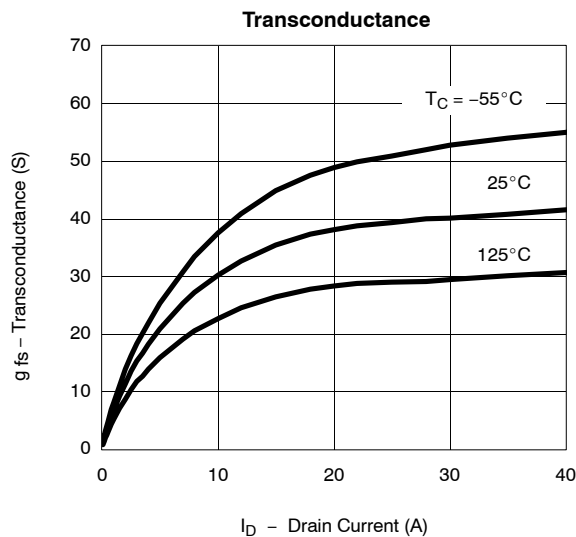
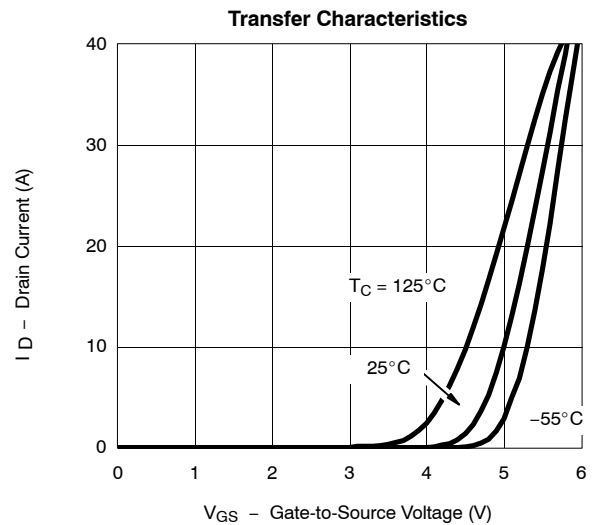
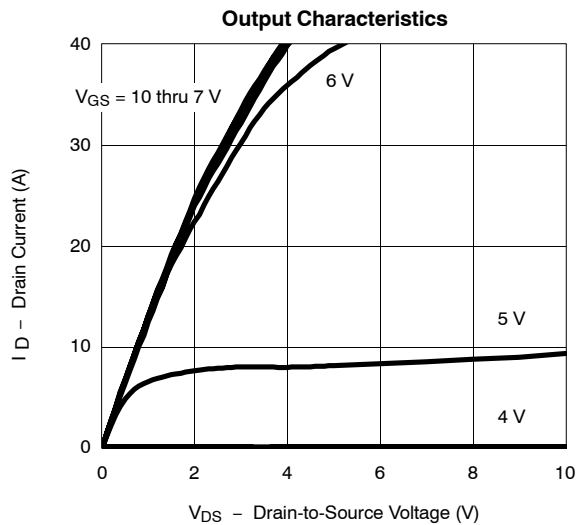
b. See SOA curve for voltage derating.

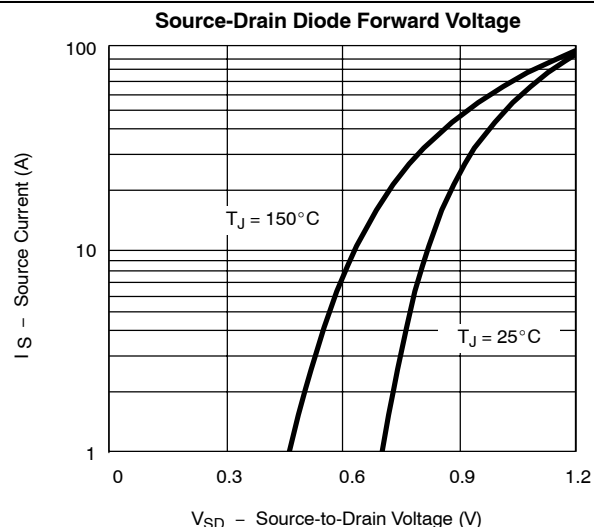
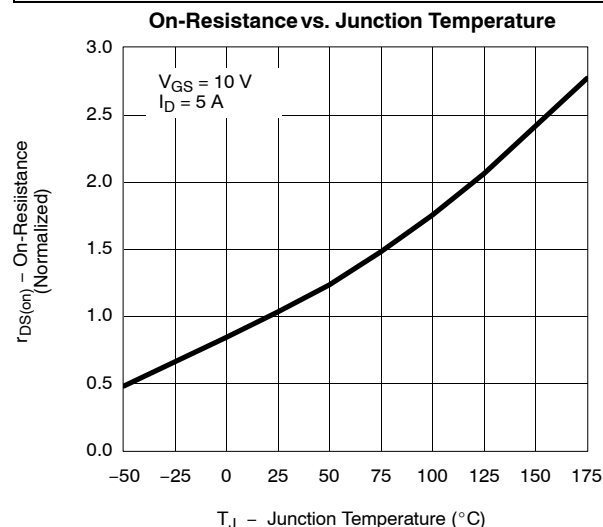
**SPECIFICATIONS (T_J = 25 °C UNLESS OTHERWISE NOTED)**

Parameter	Symbol	Test Condition	Min	Typ ^a	Max	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 250 μA	200			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	2		4	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±20 V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 200 V, V _{GS} = 0 V			1	μA
		V _{DS} = 200 V, V _{GS} = 0 V, T _J = 125°C			50	
		V _{DS} = 200 V, V _{GS} = 0 V, T _J = 175°C			250	
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	40			A
Drain-Source On-State Resistance ^b	r _{DS(on)}	V _{GS} = 10 V, I _D = 5 A		0.075	0.090	Ω
		V _{GS} = 10 V, I _D = 5 A, T _J = 125°C			0.190	
		V _{GS} = 10 V, I _D = 5 A, T _J = 175°C			0.260	
		V _{GS} = 6 V, I _D = 5 A		0.082	0.105	
Forward Transconductance ^b	g _{fs}	V _{DS} = 15 V, I _D = 19 A		35		S
Dynamic ^a						
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 25 V, F = 1 MHz		1800		pF
Output Capacitance	C _{oss}			180		
Reverse Transfer Capacitance	C _{rss}			80		
Total Gate Charge ^c	Q _g	V _{DS} = 100 V, V _{GS} = 10 V, I _D = 19 A		34	42	nC
Gate-Source Charge ^c	Q _{gs}			8		
Gate-Drain Charge ^c	Q _{gd}			12		
Gate Resistance	R _g		0.5		2.9	Ω
Turn-On Delay Time ^c	t _{d(on)}	V _{DD} = 100 V, R _L = 5.2 Ω I _D ≅ 19 A, V _{GEN} = 10 V, R _g = 2.5 Ω		15	25	ns
Rise Time ^c	t _r			50	75	
Turn-Off Delay Time ^c	t _{d(off)}			30	45	
Fall Time ^c	t _f			60	90	
Source-Drain Diode Ratings and Characteristic (T _C = 25°C)						
Pulsed Current	I _{SM}				50	A
Diode Forward Voltage ^b	V _{SD}	I _F = 19 A, V _{GS} = 0 V		0.9	1.5	V
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 19 A, di/dt = 100 A/μs		180	250	ns

Notes

- a. Guaranteed by design, not subject to production testing.
b. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.
c. Independent of operating temperature.

**TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)**

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THERMAL RATINGS
